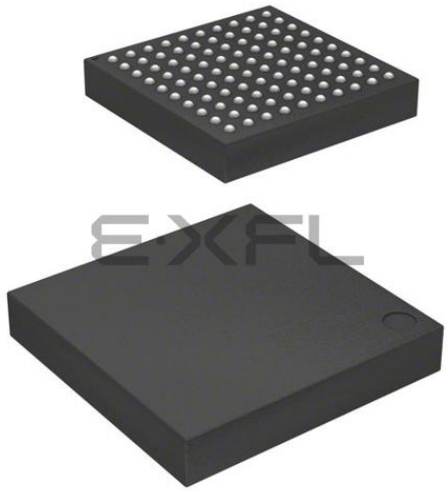
Renesas Electronics America Inc - R5F563NBCDLJ#U0 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, LINbus, SCI, SPI, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	78
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	32K x 8
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x10b, 14x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFLGA
Supplier Device Package	100-TFLGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f563nbcdlj-u0

Table 1.1 Outline of Specifications (2/6)

Classification	Module/Function	Description
Low power consumption	Low power consumption facilities	• Module stop function • Four low power consumption modes Sleep mode, all-module clock stop mode, software standby mode, and deep software standby mode • Battery backup function
Interrupt	Interrupt controller (ICUb)	• Peripheral function interrupts: 187 sources • External interrupts: 16 (pins IRQ0 to IRQ15) • Software interrupts: One source • Non-maskable interrupts: 6 sources • Sixteen levels specifiable for the order of priority
External bus extension		• The external address space can be divided into nine areas (CS0 to CS7, SDCS), each with independent control of access settings. Capacity of each area: 16 Mbytes (CS0 to CS7), 128 Mbytes (SDCS) A chip-select signal (CS0# to CS7#, SDCS#) can be output for each area. Each area is specifiable as an 8-, 16-, or 32-bit bus space. The data arrangement in each area is selectable as little or big endian (only for data). • SDRAM interface connectable • Bus format: Separate bus, multiplex bus • Wait control • Write buffer facility
DMA	DMA controller (DMAC)	• 4 channels • Three transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: Software trigger, external interrupts, and interrupt requests from peripheral functions
	EXDMA controller (EXDMACa)	• 2 channels • Four transfer modes: Normal transfer, repeat transfer, block transfer, and cluster transfer • Single-address transfer enabled with the EDAKn signal • Capable of direct data transfer to TFT LCD panels • Activation sources: Software trigger, external DMA requests (EDREQn), and interrupt requests from peripheral functions
	Data transfer controller (DTCa)	• Three transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: External interrupts and interrupt requests from peripheral functions

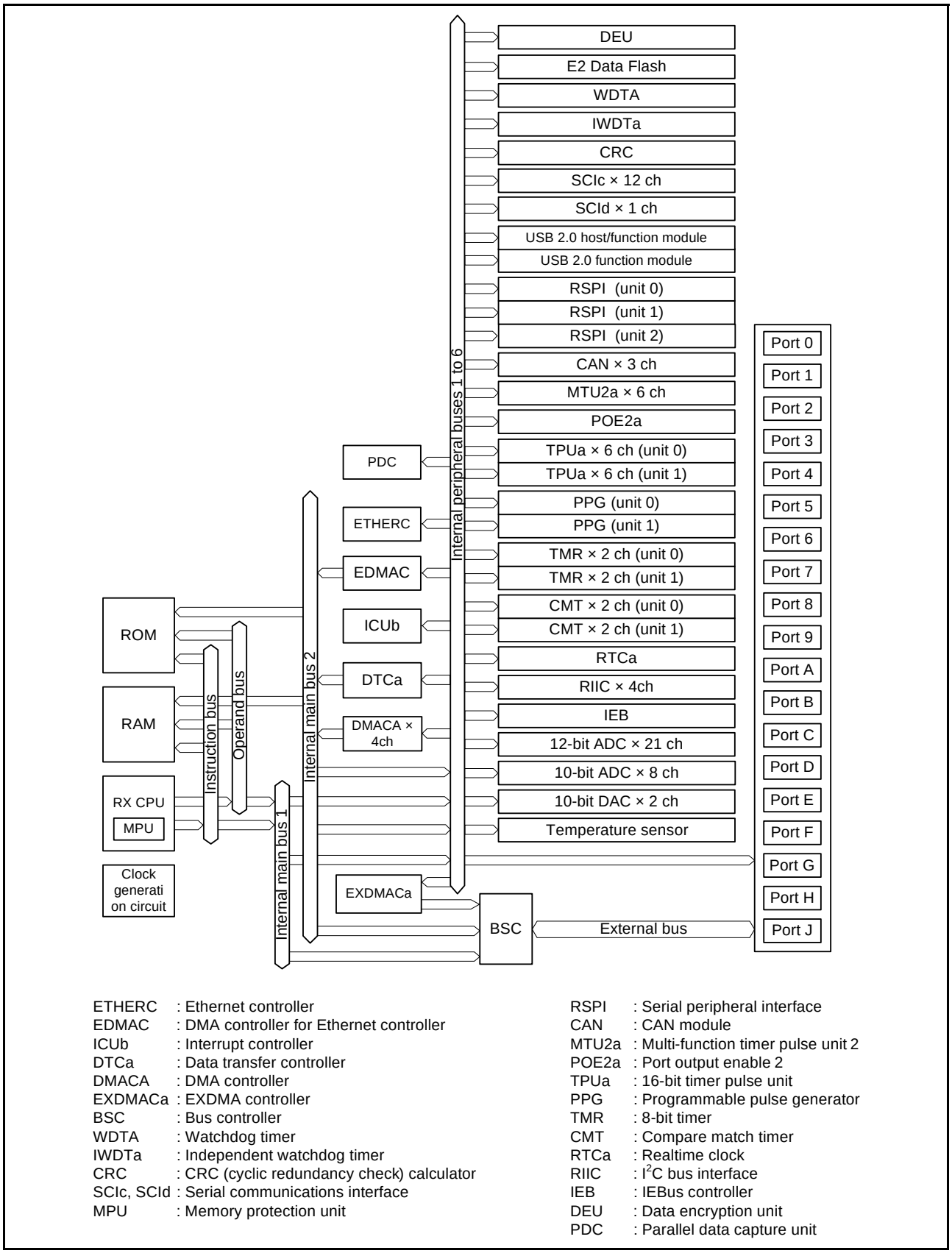
Table 1.1 Outline of Specifications (6/6)

Classification	Module/Function	Description
Communication function	Parallel data capture unit (PDC)	• 1 channel • Communicates with an image sensor or other external I/Os and transfer parallel data such as an image output from those devices to internal RAM or external address spaces (CS space and SDRAM space) through DTC or DMAC.
12-bit A/D converter (S12ADa)		• 1 unit (1 unit x 21 channels) • 12-bit resolution • Conversion time: 1.0 μs per channel (in operation with PCLK at 50 MHz) • Operating mode Scan mode (single scan mode or continuous scan mode) • Sample-and-hold function • Reference voltage generation • Three ways to start A/D conversion Conversion can be started by software, a conversion start trigger from a timer (MTU, TPU, or TMR), or an external trigger signal. • A/D conversion of the temperature sensor output
10-bit A/D converter (ADb)		• 1 unit (1 unit x 8 channels) • 10-bit resolution • Conversion time: 1.0 μs per channel (in operation with PCLK at 50 MHz) • Operating mode Scan mode (single scan mode or continuous scan mode) External amplifier connection mode • Sample-and-hold function • Three ways to start A/D conversion Conversion can be started by software, a conversion start trigger from a timer (MTU, TPU, or TMR), or an external trigger signal.
D/A converter (DAa)		• 2 channels • 10-bit resolution • Output voltage: 0 V to VREFH
Temperature sensor		• 1 channel • Precision: ±1ºC • The voltage of the temperature is converted into a digital value by the 12-bit A/D converter.
CRC calculator (CRC)		• CRC code generation for arbitrary amounts of data in 8-bit units • Select any of three generating polynomials: $X^8 + X^2 + X + 1$, $X^{16} + X^{15} + X^2 + 1$, or $X^{16} + X^{12} + X^5 + 1$. • Generation of CRC codes for use with LSB-first or MSB-first communications is selectable
Unique ID		A 16-byte device-specific ID (only for the G version)
Data encryption unit (DEU)*1		• AES encryption and decryption functions • 128/192/256-bit key length • ECB/CBC mode
Operating frequency		Up to 100 MHz
Power supply voltage		VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0, V_{BATT} = 2.0 V to 3.6 V (for products with 100 or more pins), V_{BATT} = 2.3 V to 3.6 V (for the 64-pin product)
Operating temperature		D version: -40 to +85°C, G version: -40 to +105°C*2
Package		177-pin TFLGA (PTLG0177KA-A) 176-pin LFBGA (PLBG0176GA-A) 176-pin LQFP (PLQP0176KB-A) 145-pin TFLGA (PTLG0145KA-A) 144-pin LQFP (PLQP0144KA-A) 100-pin TFLGA (PTLG0100JA-A) (in the planning stage) 100-pin LQFP (PLQP0100KB-A) 64-pin TFLGA (PTLG0064JA-A) 64-pin LQFP (PLQP0064KB-A) 48-pin LQFP (PLQP0048KB-A)
On-chip debugging system		• E1 emulator (JTAG and FINE interfaces) • E20 emulator (JTAG interface)

Note 1. Please contact our sales office for more information.
Note 2. Please contact us if you are using a G version.

1.3 Block Diagram

Figure 1.2 shows a block diagram.



ETHERC : Ethernet controller
EDMAC : DMA controller for Ethernet controller
ICUb : Interrupt controller
DTCa : Data transfer controller
DMACA : DMA controller
EXDMACa : EXDMA controller
BSC : Bus controller
WDTA : Watchdog timer
IWDTa : Independent watchdog timer
CRC : CRC (cyclic redundancy check) calculator
SCIc, SCId : Serial communications interface
MPU : Memory protection unit

RSPI : Serial peripheral interface
CAN : CAN module
MTU2a : Multi-function timer pulse unit 2
POE2a : Port output enable 2
TPUa : 16-bit timer pulse unit
PPG : Programmable pulse generator
TMR : 8-bit timer
CMT : Compare match timer
RTCa : Realtime clock
RIIC : I^2C bus interface
IEB : IEBus controller
DEU : Data encryption unit
PDC : Parallel data capture unit

Figure 1.2 Block Diagram

Table 1.7 List of Pins and Pin Functions (145-Pin TFLGA) (5/5)

Pin No. 145-pin TFLGA	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	Timers (MTU, TPU, TMR, PPG, RTC, POE)	Communications (ETHERC, SCIc, SCId, RSPI, RIIC, CAN, IEB, USB, and PDC)	Interrupt	S12AD AD DA
N7	TRDATA3	P55	WAIT#/ EDREQ0	MTIOC4D/TMO3	CRX1/ET_EXOUT	IRQ10	
N8	VSS						
N9		PC7	A23/CS0#	MTIOC3A/MTCLKB/ TIOCB6/TMO2/PO31	TXD8/SMOSI8/SSDA8/ MISOA/ET_COL	IRQ14	
N10	TRSYNC	P82	EDREQ1	MTIOC4A/PO28	TXD10/SMOSI10/SSDA10/ ET_ETXD1/RMII_TXD1		
N11		PC3	A19	MTIOC4D/TCLKB/PO24	TXD5/SMOSI5/SSDA5/ IETXD/ET_TX_ER		
N12		P75	CS5#	PO20	SCK11/ET_ERXD0/ RMII_RXD0		
N13		P74	CS4#	PO19	CTS11#/RTS11#/SS11#/ ET_ERXD1/RMII_RXD1		

Note 1. The BCLK function is multiplexed with the I/O port function for pin P53, so the port function is not available if the external bus is enabled.

Note 2. Enabled only for the ROM capacity: 2 Mbytes/1.5 Mbytes

Table 1.9 List of Pins and Pin Functions (100-Pin TFLGA) (4/5)

Pin No. 100-pin TFLGA	Power Supply Clock System Control	I/O Port	Bus EXDMAC	Timers (MTU, TPU, TMR, PPG, RTC, POE)	Communications (ETHERC, SCIc, SCId, RSPI, RIIC, CAN, IEB, USB)	Interrupt	S12AD AD DA
H4		P15		MTIOC0B/ MTCLKB/ TIOCB2/ TCLKB/TMCI2/ PO13	RXD1/SCK3/ SMISO1/SSCL1/ CRX1-DS	IRQ5	
H5		P55	WAIT#/ EDREQ0	MTIOC4D/ TMO3	CRX1/ET_EXOUT	IRQ10	
H6		P54	ALE/EDACK0	MTIOC4B/ TMCI1	CTS2#/RTS2#/ SS2#/CTX1/ ET_LINKSTA		
H7		PC7	A23/CS0#	MTIOC3A/ MTCLKB/ TMO2/PO31	TXD8/SMOSI8/ SSDA8/MISOA/ ET_COL	IRQ14	
H8		PC6	A22/CS1#	MTIOC3C/ MTCLKA/ TMCI2/PO30	RXD8/SMISO8/ SSCL8/MOSIA/ ET_ETXD3	IRQ13	
H9		PB6	A14	MTIOC3D/ TIOCA5/PO30	RXD9/SMISO9/ SSCL9/ET_ETXD1/ RMII_TXD1		
H10		PB7	A15	MTIOC3B/ TIOCB5/PO31	TXD9/SMOSI9/ SSDA9/ET_CRS/ RMII_CRS_DV		
J1		P24	CS4#/ EDREQ1	MTIOC4A/ MTCLKA/ TIOCB4/ TMRI1/PO4	SCK3/ USB0_VBUSEN		
J2		P21		MTIOC1B/ TIOCA3/ TMCI0/PO1	RXD0/SMISO0/ SSCL0/ USB0_EXICEN	IRQ9	
J3		P17		MTIOC3A/ MTIOC3B/ TIOCB0/ TCLKD/TMO1/ PO15/POE8#	SCK1/TXD3/ SMOSI3/SSDA3/ MISOA/SDA2-DS/ IETXD	IRQ7	ADTRG#
J4		P13		MTIOC0B/ TIOCA5/TMO3/ PO13	TXD2/SMOSI2/ SSDA2/SDA0[FM+]	IRQ3	ADTRG#
J5	VSS_USB						
J6	VCC_USB						
J7		P50	WR0#/WR#		TXD2/SMOSI2/ SSDA2/SSLB1		
J8		PC4	A20/CS3#	MTIOC3D/ MTCLKC/ TMCI1/PO25/ POE0#	SCK5/CTS8#/ RTS8#/SS8#/ SSLA0/ET_TX_CLK		
J9		PC0	A16	MTIOC3C/ TCLKC/PO17	CTS5#/RTS5#/ SS5#/SSLA1/ ET_ERXD3	IRQ14	
J10		PC1	A17	MTIOC3A/ TCLKD/PO18	SCK5/SSLA2/ ET_ERXD2	IRQ12	
K1		P23	EDACK0	MTIOC3D/ MTCLKD/ TIOCD3/PO3	TXD3/CTS0#/ RTS0#/SMOSI3/ SS0#/SSDA3/ USB0_DPUPE		

Table 4.1 List of I/O Registers (Address Order) (8/50)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
0008 70CBh	ICU	Interrupt request register 203	IR203	8	8	2 ICLK		ICUb
0008 70D6h	ICU	Interrupt request register 214	IR214	8	8	2 ICLK		
0008 70D7h	ICU	Interrupt request register 215	IR215	8	8	2 ICLK		
0008 70D8h	ICU	Interrupt request register 216	IR216	8	8	2 ICLK		
0008 70D9h	ICU	Interrupt request register 217	IR217	8	8	2 ICLK		
0008 70DAh	ICU	Interrupt request register 218	IR218	8	8	2 ICLK		
0008 70DBh	ICU	Interrupt request register 219	IR219	8	8	2 ICLK		
0008 70DCh	ICU	Interrupt request register 220	IR220	8	8	2 ICLK		
0008 70DDh	ICU	Interrupt request register 221	IR221	8	8	2 ICLK		
0008 70DEh	ICU	Interrupt request register 222	IR222	8	8	2 ICLK		
0008 70DFh	ICU	Interrupt request register 223	IR223	8	8	2 ICLK		
0008 70E0h	ICU	Interrupt request register 224	IR224	8	8	2 ICLK		
0008 70E1h	ICU	Interrupt request register 225	IR225	8	8	2 ICLK		
0008 70E2h	ICU	Interrupt request register 226	IR226	8	8	2 ICLK		
0008 70E3h	ICU	Interrupt request register 227	IR227	8	8	2 ICLK		
0008 70E4h	ICU	Interrupt request register 228	IR228	8	8	2 ICLK		
0008 70E5h	ICU	Interrupt request register 229	IR229	8	8	2 ICLK		
0008 70E6h	ICU	Interrupt request register 230	IR230	8	8	2 ICLK		
0008 70E7h	ICU	Interrupt request register 231	IR231	8	8	2 ICLK		
0008 70E8h	ICU	Interrupt request register 232	IR232	8	8	2 ICLK		
0008 70E9h	ICU	Interrupt request register 233	IR233	8	8	2 ICLK		
0008 70EAh	ICU	Interrupt request register 234	IR234	8	8	2 ICLK		
0008 70EBh	ICU	Interrupt request register 235	IR235	8	8	2 ICLK		
0008 70ECh	ICU	Interrupt request register 236	IR236	8	8	2 ICLK		
0008 70EDh	ICU	Interrupt request register 237	IR237	8	8	2 ICLK		
0008 70EEh	ICU	Interrupt request register 238	IR238	8	8	2 ICLK		
0008 70EFh	ICU	Interrupt request register 239	IR239	8	8	2 ICLK		
0008 70F0h	ICU	Interrupt request register 240	IR240	8	8	2 ICLK		
0008 70F1h	ICU	Interrupt request register 241	IR241	8	8	2 ICLK		
0008 70F2h	ICU	Interrupt request register 242	IR242	8	8	2 ICLK		
0008 70F3h	ICU	Interrupt request register 243	IR243	8	8	2 ICLK		
0008 70F4h	ICU	Interrupt request register 244	IR244	8	8	2 ICLK		
0008 70F5h	ICU	Interrupt request register 245	IR245	8	8	2 ICLK		
0008 70F6h	ICU	Interrupt request register 246	IR246	8	8	2 ICLK		
0008 70F7h	ICU	Interrupt request register 247	IR247	8	8	2 ICLK		
0008 70F8h	ICU	Interrupt request register 248	IR248	8	8	2 ICLK		
0008 70F9h	ICU	Interrupt request register 249	IR249	8	8	2 ICLK		
0008 70FAh	ICU	Interrupt request register 250	IR250	8	8	2 ICLK		
0008 70FBh	ICU	Interrupt request register 251	IR251	8	8	2 ICLK		
0008 70FCh	ICU	Interrupt request register 252	IR252	8	8	2 ICLK		
0008 70FDh	ICU	Interrupt request register 253	IR253	8	8	2 ICLK		
0008 711Bh	ICU	DTC activation enable register 027	DTCER027	8	8	2 ICLK		
0008 711Ch	ICU	DTC activation enable register 028	DTCER028	8	8	2 ICLK		
0008 711Dh	ICU	DTC activation enable register 029	DTCER029	8	8	2 ICLK		
0008 711Eh	ICU	DTC activation enable register 030	DTCER030	8	8	2 ICLK		
0008 711Fh	ICU	DTC activation enable register 031	DTCER031	8	8	2 ICLK		
0008 7121h	ICU	DTC activation enable register 033	DTCER033	8	8	2 ICLK		
0008 7122h	ICU	DTC activation enable register 034	DTCER034	8	8	2 ICLK		
0008 7124h	ICU	DTC activation enable register 036	DTCER036	8	8	2 ICLK		
0008 7125h	ICU	DTC activation enable register 037	DTCER037	8	8	2 ICLK		
0008 7127h	ICU	DTC activation enable register 039	DTCER039	8	8	2 ICLK		

Table 4.1 List of I/O Registers (Address Order) (20/50)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
0008 8368h	RIIC3	I²C bus status register 1	ICSR1	8	8	2, 3 PCLKB	2 ICLK	RSPI
0008 8369h	RIIC3	I²C bus status register 2	ICSR2	8	8	2, 3 PCLKB	2 ICLK	
0008 836Ah	RIIC3	Slave address register L0	SARL0	8	8	2, 3 PCLKB	2 ICLK	
0008 836Bh	RIIC3	Slave address register U0	SARU0	8	8	2, 3 PCLKB	2 ICLK	
0008 836Ch	RIIC3	Slave address register L1	SARL1	8	8	2, 3 PCLKB	2 ICLK	
0008 836Dh	RIIC3	Slave address register U1	SARU1	8	8	2, 3 PCLKB	2 ICLK	
0008 836Eh	RIIC3	Slave address register L2	SARL2	8	8	2, 3 PCLKB	2 ICLK	
0008 836Fh	RIIC3	Slave address register U2	SARU2	8	8	2, 3 PCLKB	2 ICLK	
0008 8370h	RIIC3	I²C bus bit rate low-level register	ICBRL	8	8	2, 3 PCLKB	2 ICLK	
0008 8371h	RIIC3	I²C bus bit rate high-level register	ICBRH	8	8	2, 3 PCLKB	2 ICLK	
0008 8372h	RIIC3	I²C bus transmit data register	ICDRT	8	8	2, 3 PCLKB	2 ICLK	
0008 8373h	RIIC3	I²C bus receive data register	ICDRR	8	8	2, 3 PCLKB	2 ICLK	
0008 8380h	RSPI0	RSPI control register	SPCR	8	8	2, 3 PCLKB	2 ICLK	
0008 8381h	RSPI0	RSPI slave select polarity register	SSLP	8	8	2, 3 PCLKB	2 ICLK	
0008 8382h	RSPI0	RSPI pin control register	SPPCR	8	8	2, 3 PCLKB	2 ICLK	
0008 8383h	RSPI0	RSPI status register	SPSR	8	8	2, 3 PCLKB	2 ICLK	
0008 8384h	RSPI0	RSPI data register	SPDR	32	16, 32	2, 3 PCLKB	2 ICLK	
0008 8388h	RSPI0	RSPI sequence control register	SPSCR	8	8	2, 3 PCLKB	2 ICLK	
0008 8389h	RSPI0	RSPI sequence status register	SPSSR	8	8	2, 3 PCLKB	2 ICLK	
0008 838Ah	RSPI0	RSPI bit rate register	SPBR	8	8	2, 3 PCLKB	2 ICLK	
0008 838Bh	RSPI0	RSPI data control register	SPDCR	8	8	2, 3 PCLKB	2 ICLK	
0008 838Ch	RSPI0	RSPI clock delay register	SPCKD	8	8	2, 3 PCLKB	2 ICLK	
0008 838Dh	RSPI0	RSPI slave select negation delay register	SSLND	8	8	2, 3 PCLKB	2 ICLK	
0008 838Eh	RSPI0	RSPI next-access delay register	SPND	8	8	2, 3 PCLKB	2 ICLK	
0008 838Fh	RSPI0	RSPI control register 2	SPCR2	8	8	2, 3 PCLKB	2 ICLK	
0008 8390h	RSPI0	RSPI command register 0	SPCMD0	16	16	2, 3 PCLKB	2 ICLK	
0008 8392h	RSPI0	RSPI command register 1	SPCMD1	16	16	2, 3 PCLKB	2 ICLK	
0008 8394h	RSPI0	RSPI command register 2	SPCMD2	16	16	2, 3 PCLKB	2 ICLK	
0008 8396h	RSPI0	RSPI command register 3	SPCMD3	16	16	2, 3 PCLKB	2 ICLK	
0008 8398h	RSPI0	RSPI command register 4	SPCMD4	16	16	2, 3 PCLKB	2 ICLK	
0008 839Ah	RSPI0	RSPI command register 5	SPCMD5	16	16	2, 3 PCLKB	2 ICLK	
0008 839Ch	RSPI0	RSPI command register 6	SPCMD6	16	16	2, 3 PCLKB	2 ICLK	RSPI
0008 839Eh	RSPI0	RSPI command register 7	SPCMD7	16	16	2, 3 PCLKB	2 ICLK	
0008 83A0h	RSPI1	RSPI control register	SPCR	8	8	2, 3 PCLKB	2 ICLK	
0008 83A1h	RSPI1	RSPI slave select polarity register	SSLP	8	8	2, 3 PCLKB	2 ICLK	
0008 83A2h	RSPI1	RSPI pin control register	SPPCR	8	8	2, 3 PCLKB	2 ICLK	
0008 83A3h	RSPI1	RSPI status register	SPSR	8	8	2, 3 PCLKB	2 ICLK	
0008 83A4h	RSPI1	RSPI data register	SPDR	32	16, 32	2, 3 PCLKB	2 ICLK	
0008 83A8h	RSPI1	RSPI sequence control register	SPSCR	8	8	2, 3 PCLKB	2 ICLK	
0008 83A9h	RSPI1	RSPI sequence status register	SPSSR	8	8	2, 3 PCLKB	2 ICLK	
0008 83AAh	RSPI1	RSPI bit rate register	SPBR	8	8	2, 3 PCLKB	2 ICLK	
0008 83ABh	RSPI1	RSPI data control register	SPDCR	8	8	2, 3 PCLKB	2 ICLK	
0008 83ACh	RSPI1	RSPI clock delay register	SPCKD	8	8	2, 3 PCLKB	2 ICLK	
0008 83ADh	RSPI1	RSPI slave select negation delay register	SSLND	8	8	2, 3 PCLKB	2 ICLK	
0008 83AEh	RSPI1	RSPI next-access delay register	SPND	8	8	2, 3 PCLKB	2 ICLK	
0008 83AFh	RSPI1	RSPI control register 2	SPCR2	8	8	2, 3 PCLKB	2 ICLK	
0008 83B0h	RSPI1	RSPI command register 0	SPCMD0	16	16	2, 3 PCLKB	2 ICLK	
0008 83B2h	RSPI1	RSPI command register 1	SPCMD1	16	16	2, 3 PCLKB	2 ICLK	
0008 83B4h	RSPI1	RSPI command register 2	SPCMD2	16	16	2, 3 PCLKB	2 ICLK	
0008 83B6h	RSPI1	RSPI command register 3	SPCMD3	16	16	2, 3 PCLKB	2 ICLK	
0008 83B8h	RSPI1	RSPI command register 4	SPCMD4	16	16	2, 3 PCLKB	2 ICLK	

Table 5.3 DC Characteristics (2)

Conditions: VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0,
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0 V, $T_a = T_{opr}$

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Output high voltage	All output pins	V_{OH}	VCC – 0.5	—	—	V	I_{OH} = –1 mA
Output low voltage	All output pins (except for RIIC pins, and ETHERC)	V_{OL}	—	—	0.5	V	I_{OL} = 1.0 mA
	RIIC pins		—	—	0.4	V	I_{OL} = 3.0 mA
			—	—	0.6		I_{OL} = 6.0 mA
	RIIC pins (only P12 and P13 in channel 0)	V_{OL}	—	—	0.4	V	I_{OL} = 15.0 mA (ICFER.FMPE = 1)
			—	0.4	—		I_{OL} = 20.0 mA (ICFER.FMPE = 1)
	ETHERC	V_{OL}	—	—	0.4	V	I_{OL} = 1.0 mA
Input leakage current	RES#, MD pin, EMLE*1, NMI	$\lvert I_{in} \rvert$	—	—	1.0	µA	V_{in} = 0 V V_{in} = VCC
Three-state leakage current (off state)	Other than ports for 5 V tolerant	$\lvert I_{TSI} \rvert$	—	—	1.0	µA	V_{in} = 0 V V_{in} = VCC
	Ports for 5 V tolerant		—	—	5.0		Vin = 0 V Vin = 5.5 V
Input pull-up MOS current	Ports 0 to 2, 30 to 34, 36, 37, 4 to G, J3, J5	I_p	–10	—	–300	µA	VCC= 2.7 to 3.6 V V_{in} = 0 V
Input capacitance	All input pins (except for ports 12, 13, 16, 17, 20, 21, 4, C0, C1, and EMLE)	C_{in}	—	—	15	pF	V_{in} = 0 V f = 1 MHz T_a = 25°C
	Ports 12, 13, 16, 17, 20, 21, 4, C0, C1, EMLE		—	—	30		
Input pull-down MOS current	EMLE, BSCANP	I_p	10	—	300	µA	V_{in} = VCC

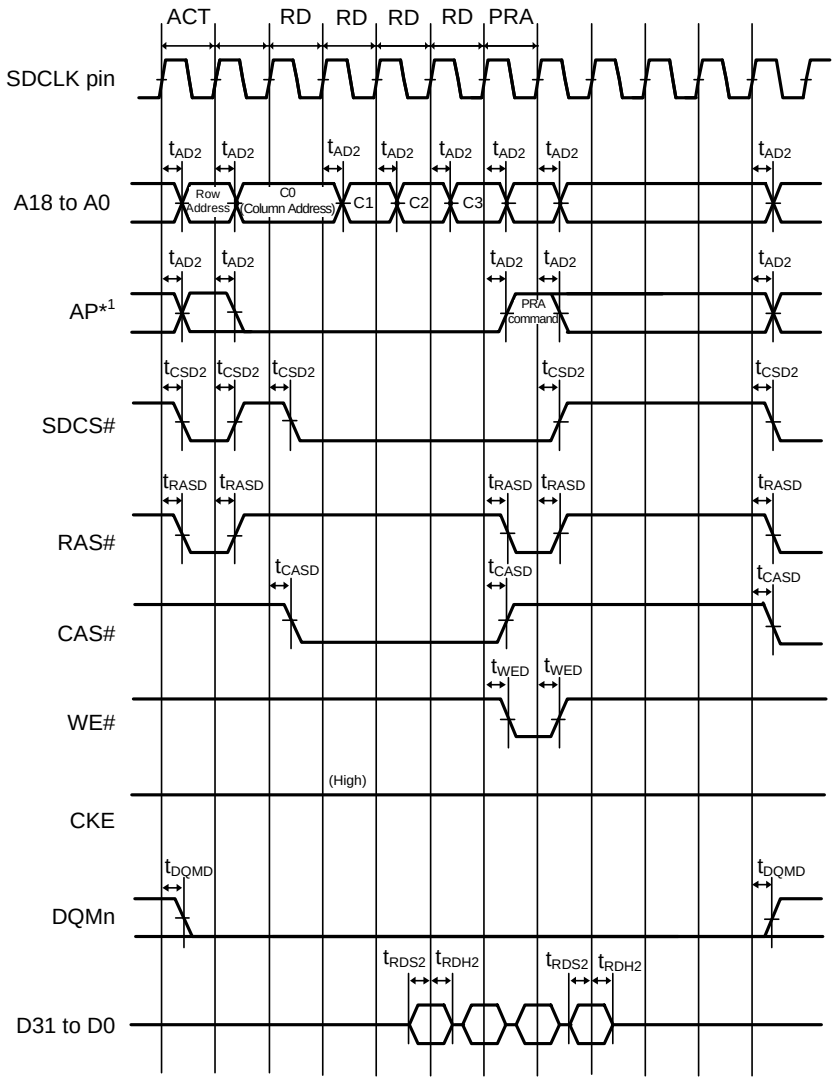
Note 1. The input leakage current value at the EMLE pin is only when V_{in} = 0 V.

5.3.2 Clock Timing

Table 5.12 Clock Timing (Except for Sub-Clock Related)

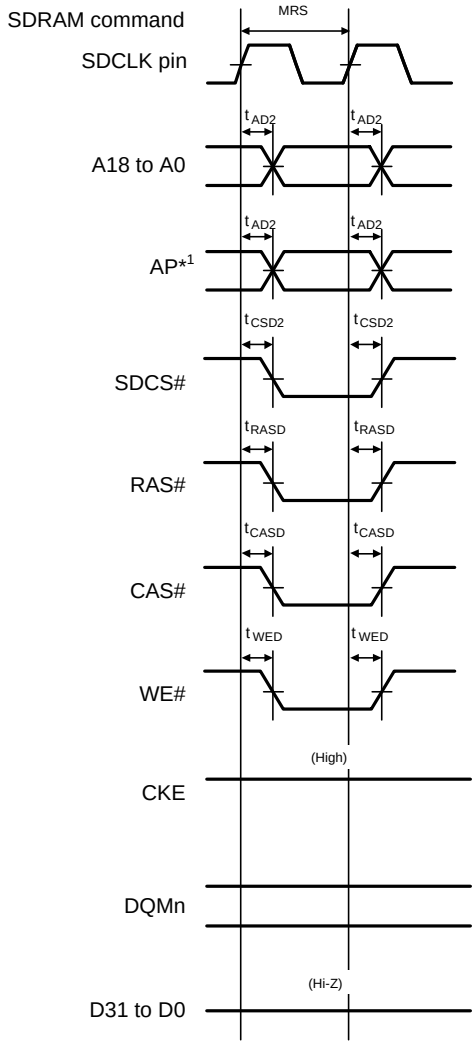
Conditions: VCC = AVCC0 = VREFH = VCC_USB = V_{BATT} = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0,
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0 V, $T_a = T_{opr}$

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BCLK pin output cycle time	Packages with 177 to 144 pins	t_{Bcyc}	20	—	—	ns	Figure 5.3
	Packages with 100 pins or less		40	—	—	ns	
BCLK pin output high pulse width		t_{CH}	5	—	—	ns	
BCLK pin output low pulse width		t_{CL}	5	—	—	ns	
BCLK pin output rising time		t_{Cr}	—	—	5	ns	
BCLK pin output falling time		t_{Cf}	—	—	5	ns	
SDCLK pin output cycle time	only 177 to 144 pin	t_{Bcyc}	20	—	—	ns	
SDCLK pin output high pulse width		t_{CH}	5	—	—	ns	
SDCLK pin output low pulse width		t_{CH}	5	—	—	ns	
SDCLK pin output rising time		t_{CH}	—	—	5	ns	
SDCLK pin output falling time		t_{CH}	—	—	5	ns	
EXTAL external clock input cycle time		t_{EXcyc}	50	—	—	ns	Figure 5.4
EXTAL external clock input high pulse width		t_{EXH}	20	—	—	ns	
EXTAL external clock input low pulse width		t_{EXL}	20	—	—	ns	
EXTAL external clock rising time		t_{EXr}	—	—	5	ns	
EXTAL external clock falling time		t_{EXf}	—	—	5	ns	
EXTAL external clock input wait time*1		t_{EXWT}	1	—	—	ms	
Main clock frequency		f_{MAIN}	4	—	16	MHz	
Main clock oscillator start-up time		$t_{MAINOSC}$	—	—	—*3	ms	Figure 5.5
Main clock oscillation stabilization wait time		$t_{MAINOSCWT}$	—	—	—*4	ms	
LOCO and IWDTCLK clock cycle time		t_{cyc}	6.96	8	9.4	µs	
LOCO and IWDTCLK clock oscillation frequency		f_{LOCO}	106.25	125	143.75	kHz	
LOCO and IWDTCLK clock oscillation stabilization wait time		t_{LOCOWT}	—	—	20	µs	Figure 5.6
HOCO clock oscillator oscillation frequency		f_{HOCO}	45	50	55	MHz	
HOCO clock oscillation stabilization wait time 1*2		$t_{HOCOWT1}$	—	—	1.8	ms	Figure 5.7
HOCO clock oscillation stabilization wait time 2		$t_{HOCOWT2}$	—	—	2.0	ms	Figure 5.8
HOCO clock power supply settling time		t_{HOCOP}	—	—	1	ms	Figure 5.9
PLL clock frequency		f_{PLL}	104	—	200	MHz	
PLL lock time	PLL operation started after main clock oscillation has settled	t_{PLL1}	—	—	500	µs	Figure 5.10
PLL clock oscillation stabilization wait time		t_{PLLWT1}	—	—	—*5	ms	
PLL lock time	PLL operation started before main clock oscillation has settled	t_{PLL2}	—	—	$t_{MAINOSC}$ +t_{PLL1}	ms	Figure 5.11
PLL clock oscillation stabilization wait time		t_{PLLWT2}	—	—	—*5	ms	



Note 1: Address pins for output of the precharge-setting command (Precharge-sel) for SDRAM.

Figure 5.26 SDRAM Space Multiple Read Bus Timing



Note 1: Address pins for output of the precharge-setting command (Precharge-sel) for SDRAM.

Figure 5.29 SDRAM Space Mode Register Set Bus Timing

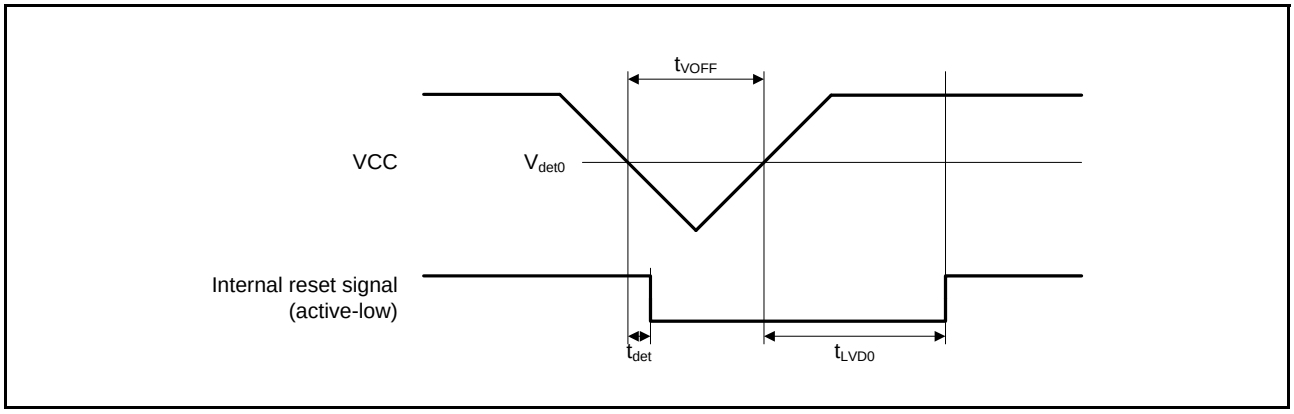


Figure 5.64 Voltage Detection Circuit Timing (V_{det0})

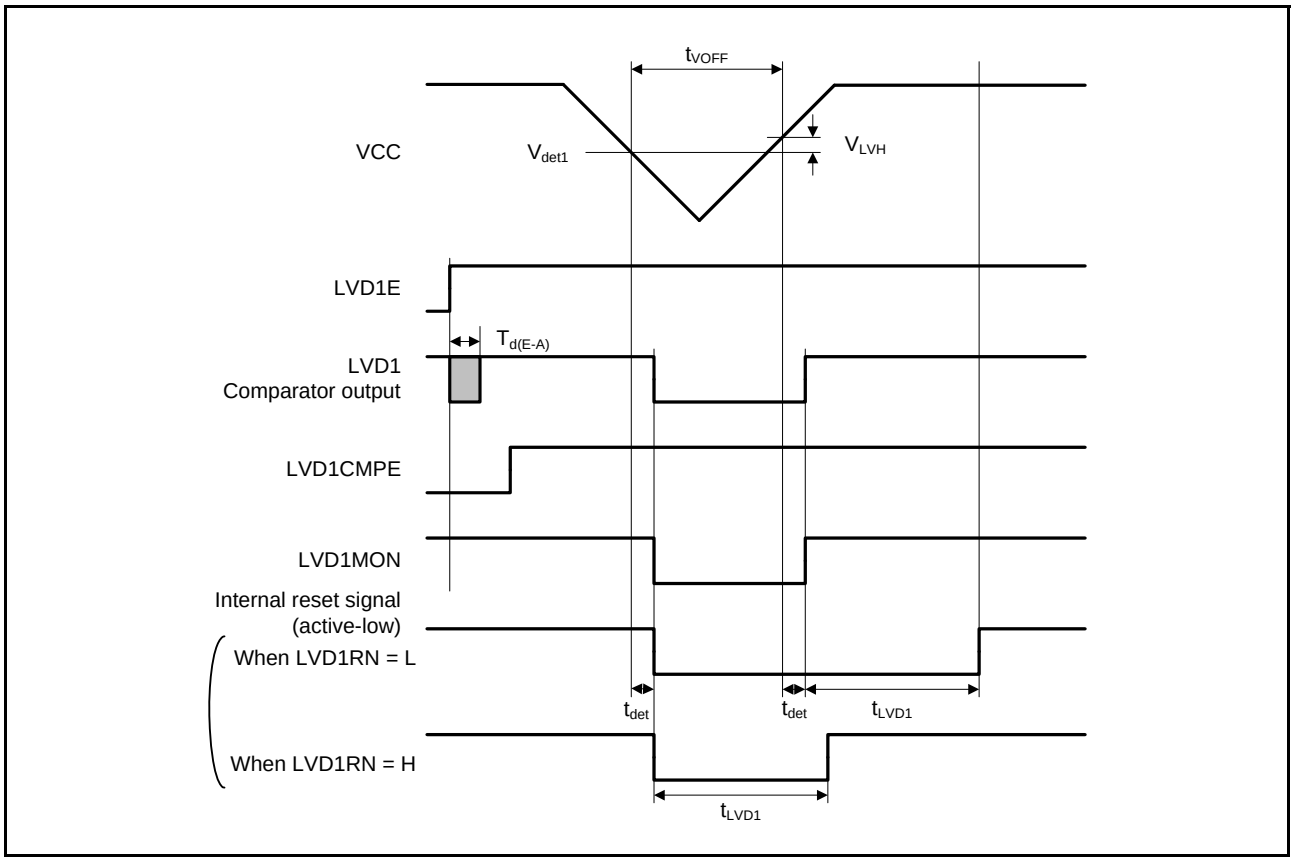


Figure 5.65 Voltage Detection Circuit Timing (V_{det1})

5.12 E^2 Flash Characteristics

Table 5.38 E2 Flash Characteristics (1)

Conditions: VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6V, VREFH0 = 2.7V to AVCC0
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0V
Temperature range for the programming/erasure operation: $T_a = T_{opr}$

Item	Symbol	min	typ	max	Unit	Condition
Reprogram/erasure cycle*1	N_{DPEC}	100000	—	—	Times	
Data hold time	t_{DDRP}	30*2	—	—	Year	Ta = +85°C

Note 1. Definition of reprogram/erase cycle:
The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 100000), erasing can be performed n times for each block. For instance, when 128-byte programming is performed 16 times for different addresses in 2-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).
Note 2. The result obtained from the reliability test.

Table 5.39 E^2 Flash Characteristics (2)

Conditions: VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0 V
Temperature range for the programming/erasure operation: $T_a = T_{opr}$

Item		Symbol	FCLK = 4 MHz			20 MHz ≤ FCLK ≤ 50 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time $N_{PEC} \leq 100$ times	2 bytes	t_{DP2}	—	0.7	6	—	0.25	2	ms
Programming time $N_{PEC} > 100$ times	2 bytes	t_{DP2}	—	0.7	6	—	0.25	2	ms
Erasure time $N_{PEC} \leq 100$ times	32 bytes	t_{DE32}	—	4	40	—	2	20	ms
Erasure time $N_{PEC} > 100$ times	32 bytes	t_{DE32}	—	7	40	—	4	20	ms
Blank check time	2 bytes	t_{DBC2}	—	—	100	—	—	30	µs
Suspend delay time during programming		t_{DSPD}	—	—	250	—	—	120	µs
First suspend delay time during erasure (in suspend priority mode)		t_{DSESD1}	—	—	250	—	—	120	µs
Second suspend delay time during erasure (in suspend priority mode)		t_{DSESD2}	—	—	500	—	—	300	µs
Suspend delay time during erasure (in erasure priority mode)		t_{DSEED}	—	—	500	—	—	300	µs

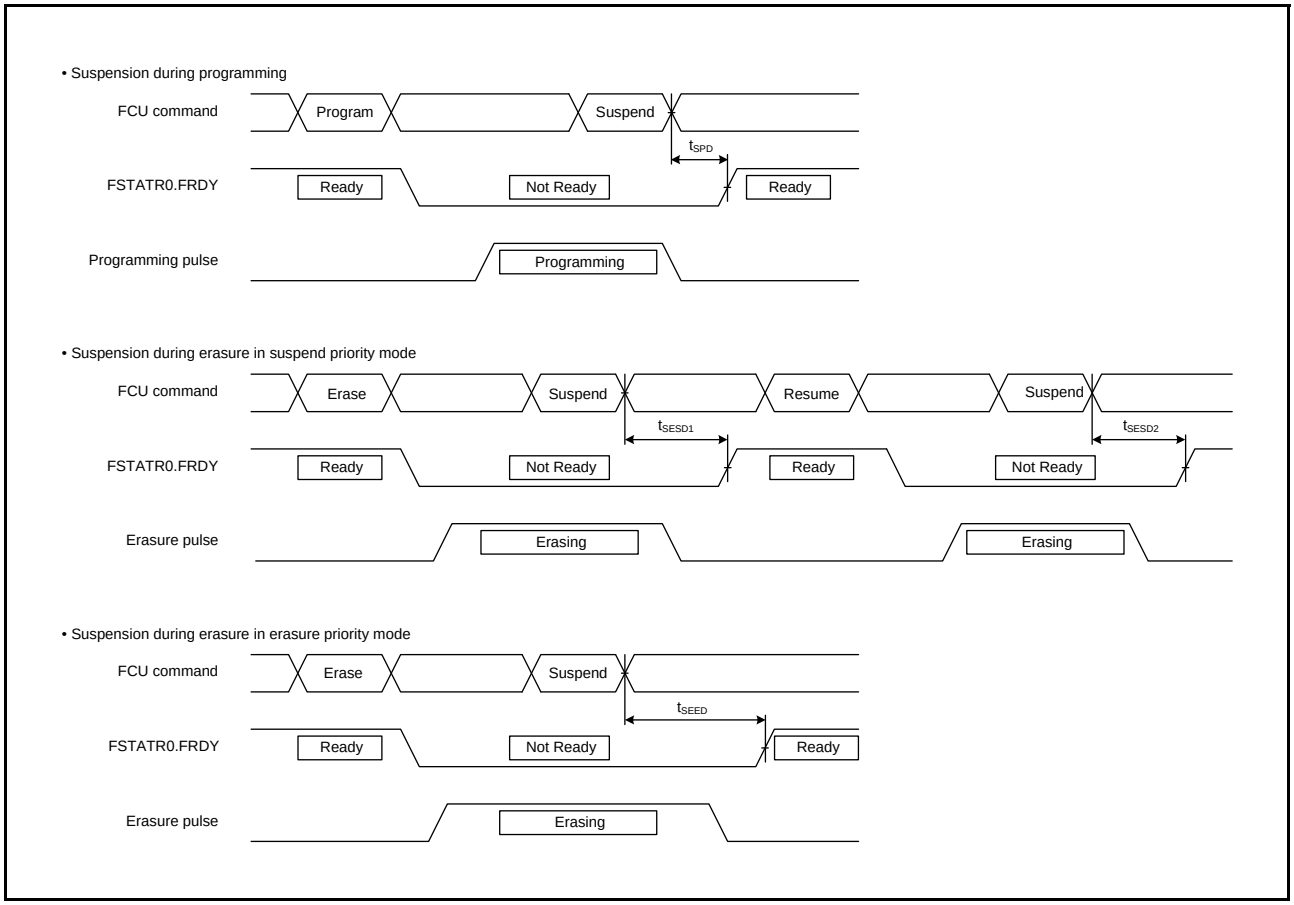
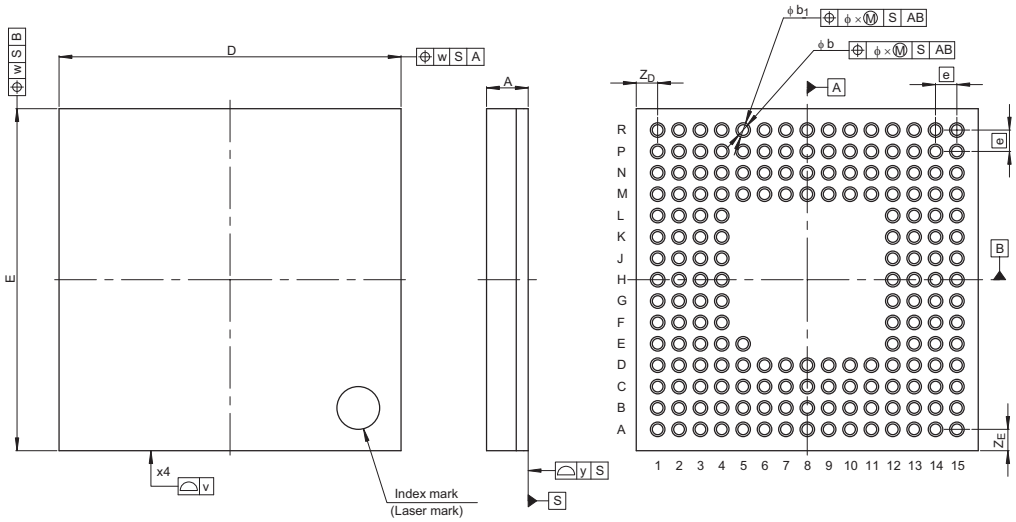


Figure 5.69 Flash Memory Program/Erase Suspend Timing

Appendix 1. Package Dimensions

Information on the latest version of the package dimensions or mountings has been displayed in “Packages” on Renesas Electronics Corporation website.

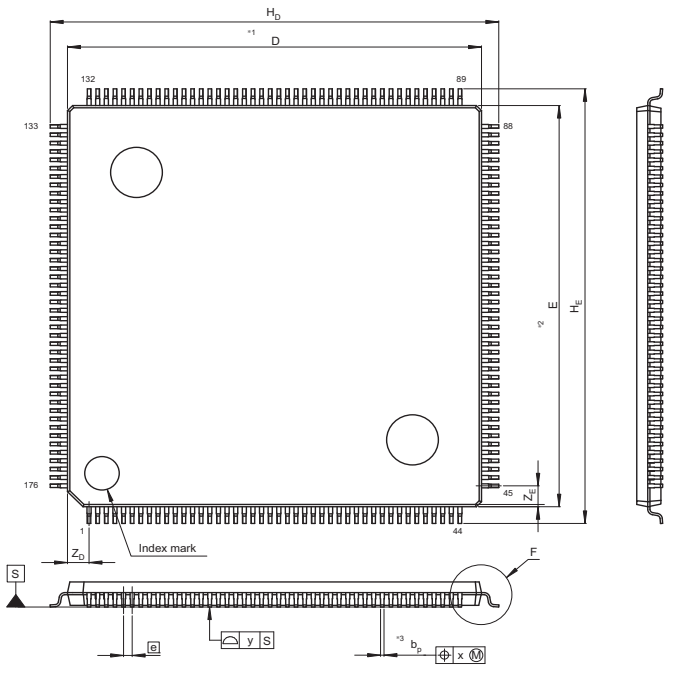
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA177-8x8-0.50	PTLG0177KA-A	177F0E-A	0.2g

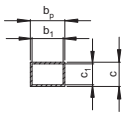


Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.0	—
E	—	8.0	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.5	—
b	0.21	0.25	0.29
b_1	0.29	0.34	0.39
x	—	—	0.08
y	—	—	0.08
Z_D	—	0.5	—
Z_E	—	0.5	—

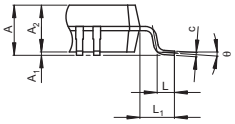
Figure A 177-pin TFLGA (PTLG0177KA-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP176-24x24-0.50	PLQP0176KB-A	176P6Q-A/FP-176E/FP-176EV	1.8g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	23.9	24.0	24.1
E	23.9	24.0	24.1
A_2	—	1.4	—
H_D	25.8	26.0	26.2
H_E	25.8	26.0	26.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure C 176-pin LQFP (PLQP0176KB-A)

REVISION HISTORY — RX63N Group, RX631 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.50	May 13. 2011	—	First Edition issued
0.90	Dec 27. 2011	All	
		—	Package added (177-pin TFLGA, 176-pin LFBGA, 145-pin TFLGA), module name changed
		—	Interrupt Controller (ICUb) module name changed
		1. Overview	
		2 to 6	Table 1.1 Outline of Specifications, Reset, Realtime clock, Temperature sensor, Power supply voltage, changed
		8 to 10	Table 1.3 List of Products, changed
		10	Figure 1.1 How to Read the Product Part No., changed
		12 to 17	Table 1.4 Pin Functions, BSCANP pin added
		18	Figure 1.3 Pin Assignment (176-Pin TFLGA), added
		19	Figure 1.4 Pin Assignment (176-Pin LFBGA), added
		20	Figure 1.5 Pin Assignment (176-Pin LQFP), pin 18 changed
		21	Figure 1.6 Pin Assignment (144-Pin TFLGA), added
		22	Figure 1.7 Pin Assignment (144-Pin LQFP), pin 16 changed
		23	Figure 1.8 Pin Assignment (100-Pin LQFP), pin 7 changed
		24 to 28	Table 1.5 List of Pins and Pin Functions (177-pin TFLGA, 176-pin LFBGA), added
		34 to 38	Table 1.7 List of Pins and Pin Functions (145-Pin TFLGA), added
		4. I/O Registers	
		56 to 99	Table 5.1 List of I/O Registers, changed
		Appendix 2. Package Dimensions	
		100	Figure A. 177-pin TFLGA (PTLG0177KA-A), added
		101	Figure B. 176-pin LFBGA (PLBG0176GA-A), added
		103	Figure D. 145-pin TFLGA (PTLG0145KA-A), added
		105	Figure F. 100-pin TFLGA (PTLG0100KA-A), added
1.00	Jun 06. 2012	1. Overview	
		2 to 6	Table1.1 Outline of Specifications: CPU, ROM, RAM, E2 DataFlash, clock generation circuit, temperature sensor, power supply voltage, changed. Low power consumption, deleted
		8 to 10	Table1.3 List of Products, changed
		11	Figure 1.2 Block Diagram, changed
		12	Table1.4 Pin Functions, description of VCC, changed
		24 to 28	Table 1.5 List of Pin and Pin Functions (177-Pin TFLGA, 176-Pin LFBGA): SDRAMC, added to table header; BCLK in pin number line M8, moved to Power Supply Clock System Control column
		29 to 33	Table 1.6 List of Pin and Pin Functions (176-Pin LQFP): SDRAMC, added to table header; BCLK in pin number line 68, moved to Power Supply Clock System Control column
		34 to 38	Table 1.7 List of Pin and Pin Functions (145-Pin TFLGA): SDRAMC, added to table header; MOSIB, added to pin number line D13; T_ERXD1 in pin number line H12, changed to ET_ERXD1; PO8, added to pin number line J4; BCLK in pin number line K6, moved to Power Supply Clock System Control column
		39 to 43	Table 1.8 List of Pins and Pin Functions (144-Pin LQFP): SDRAMC, added to table header; PO8, added to pin number line 29; BCLK in pin number line 53, moved to Power Supply Clock System Control column; T_ERXD1 in pin number 87, changed to ET_ERXD1; MOSIB, added to pin number line 102
		44 to 47	Table 1.9 List of Pins and Pin Functions (100-Pin LQFP): BCLK in pin number line 41, moved to Power Supply Clock System Control column
		4. I/O Registers	
		57, 58	Table4.1, MPU registers, added
		5. Electrical Characteristics	
		105 to 163	Added

Rev.	Date	Description	
		Page	Summary
1.60	Mar 13. 2013	Feature	
		1	Changed
		1. Overview	
		2 to 7	Table 1.1 Outline of Specifications: changed, note added
		8	Table1.2 Comparison of Functions for Different Packages in the RX63N/RX631 Group, changed
		9 to 15	Table 1.3 List of Products, changed
		16	Figure 1.1 How to Read the Product Part No., changed
		17	Figure 1.2 Block Diagram, changed
		24 to 32	Figure 1.3 to Figure 1.11 Pin Assignment: note, added
		53 to 57	Table 1.9 List of Pins and Pin Functions (100-Pin TFLGA), added
		62 to 64	Table 1.11 List of Pins and Pin Functions (64-Pin LQFP), added
		65, 66	Table 1.12 List of Pins and Pin Functions (48-Pin LQFP), added
		3. Address Space	
		71	Figure 3.1 Memory Map in Each Operating Mode, changed
		4. I/O Registers	
		75 to 120	Table 4.1 List of I/O Registers (Address Order), changed
		5. Electrical Characteristics	
		All	Characteristics and timing conditions in the tables, changed
		124, 125	Table 5.4 DC Characteristics (3), changed
		126	Table 5.5 DC Characteristics (4), changed
		127	5.3 AC Characteristics, changed
		130, 131	Table 5.11, Clock Timing (Except for Sub-Clock Related): Condition and the table, changed, note, added
		132	Table 5.12 Clock Timing (Sub-Clock Related): Condition and the table, changed, note, added
		176	Table 5.33 Battery Backup Function Characteristics: Condition, changed
		Appendix 1.Package Dimensions	
		189	Figure H 64-pin LQFP (PLQP0064KB-A), added
		190	Figure I 48-pin LQFP (PLQP0048KB-A), added
1.70	Oct 08. 2013	Features	
		1	changed
		1. Overview	
		2 to 7	Table 1.1 Outline of Specifications, General I/O ports, Packages, changed, Parallel data capture unit (PDC), added.
		8	Table 1.2 Comparison of Functions for Different Packages in the RX63N/RX631 Group, 64-pin LQFP, changed, 64-pin TFLGA, Parallel data capture unit (PDC), added.
		9 to 16	Table 1.3 List of Products, changed.
		17	Figure 1.1 How to Read the Product Part No., changed
		18	Figure 1.2 Block Diagram, changed
		19 to 24	Table 1.4 Pin Functions,changed, Parallel data capture unit (PDC), added
		32	Figure 1.10 Pin Assignment (64-Pin TFLGA), added
		35 to 40	Table 1.5 List of Pin and Pin Functions (177-Pin TFLGA, 176-Pin LFBGA), changed
		41 to 45	Table 1.6 List of Pin and Pin Functions (176-Pin LQFP), changed
		46 to 50	Table 1.7 List of Pins and Pin Functions (145-Pin TFLGA), changed
		51 to 55	Table 1.8 List of Pins and Pin Functions (144-Pin LQFP), changed
		65 to 66	Table 1.11 List of Pins and Pin Functions (64-Pin TFLGA), added
		3. Address Space	
		76	Figure 3.1 Memory Map in Each Operating Mode, changed
		4. I/O Registers	
		79	(4) Restrictions in Relation to RMPA and String-Manipulation Instructions, added

Classifications

- Items with Technical Update document number: Changes according to the corresponding issued Technical Update
- Items without Technical Update document number: Minor changes that do not require Technical Update to be issued

Rev.	Date	Description		Classification
		Page	Summary	
1.80	May 13. 2014	Features		
		1	Operating temp. range chaged, Unique ID added	
		1. Overview		
		2 to 7	Table 1.1 Outline of Specifications: Operating temperature changed, Unique ID and Note 2, added	
		8	Table 1.2 Comparison of Functions for Different Packages: Unique ID, added	
		9 to 16	Table 1.3 List of Products, changed and Note 2, added	TN-RX*-A092A/J
		17	Figure 1.1 How to Read the Product Part Number: Operating temperature range, changed	
		19, 23	Table 1.4 Pin Functions: VBATT and USB power pins, changed	
		3. Address Space		
		76	Figure 3.1 Memory Map in Each Operating Mode, changed	TN-RX*-A081A/E
		77	Figure 3.2 Correspondence between External Address Spaces and CS Areas (In On-Chip ROM Disabled Extended Mode), changed	TN-RX*-A081A/E
		5. Electrical Characteristics		
		130	Table 5.1 Absolute Maximum Ratings: Operating temperature, changed	
		131	Table 5.2 DC Characteristics (1): Note 1, chaged	
		133 to 134	Table 5.4 DC Characteristics (3) (for D and G Versions (-40 ≤ Ta ≤ +85°C)): Title	
		135 to 136	Table 5.5 DC Characteristics (4) (for G Version (-85 < Ta ≤ +105°C)), added	
		1921	Table 5.12 Clock Timing (Except for Sub-Clock Related): LOCO changed to LOCO and IWDTCLKB	TN-RX*-A097A/J
		144	Figure 5.6 LOCO, IWDTCLK Clock Oscillation Start Timing, added	TN-RX*-A097A/J
		189	Figure 5.68 Battery Backup Function Characteristics changed	

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